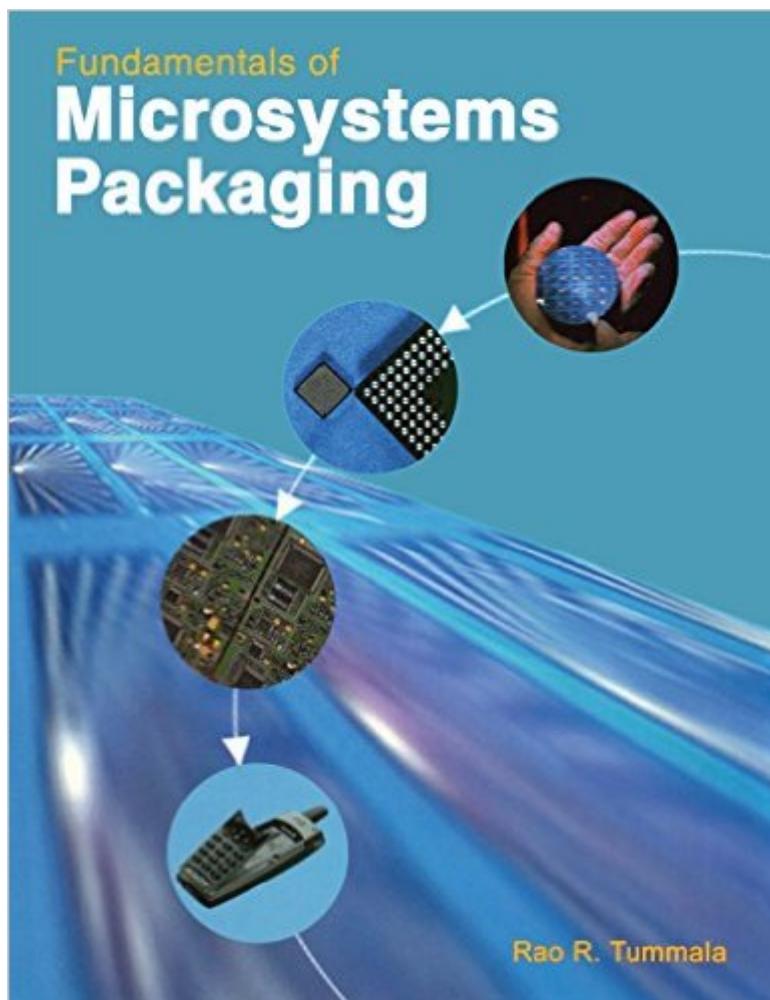


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# Fundamentals Of Microsystems Packaging



## Synopsis

LEARN ABOUT MICROSYSTEMS PACKAGING FROM THE GROUND UP Written by Rao Tummala, the field's leading author, *Fundamentals of Microsystems Packaging* is the only book to cover the field from wafer to systems, including every major contributing technology. This rigorous and thorough introduction to electronic packaging technologies gives you a solid grounding in microelectronics, photonics, RF, packaging design, assembly, reliability, testing, and manufacturing and its relevance to both semiconductors and systems. You'll find:

- \*Full coverage of electrical, mechanical, chemical, and materials aspects of each technology
- \*Easy-to-read schematics and block diagrams
- \*Fundamental approaches to all system issues
- \*Examples of all common configurations and technologies •wafer level packaging, single chip, multichip, RF, opto-electronic, microvia boards, thermal and others
- \*Details on chip-to-board connections, sealing and encapsulation, and manufacturing processes
- \*Basics of electrical and reliability testing

## Book Information

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## Customer Reviews

"*Fundamentals of Microsystems Packaging*" is an informative, well-written textbook, the first to cover this rapidly-evolving technology. Professor Tummala's latest book should appeal to only three groups: those who know a lot about microsystems packaging, those who know something about it, and those who know nothing about it. Microsystems packaging specialists, who typically focus on one sub-specialty, will find this detailed exposition of the entire field broadening. Non-specialists

with some general packaging knowledge will find here all that they need to fully understand and work with the key elements of microsystems packaging. Novices, students, and those in related technical fields will find a well-structured introduction that prepares them to deal with microsystems packaging. This comprehensive textbook offers to all of the above groups a firm grounding in the diverse disciplines comprising microsystems packaging. Nineteen of the chapters share the title, "Fundamentals of ...". "Fundamental" means "a foundation," and that is what these chapters provide, covering the key elements of topics ranging from semiconductors to systems, including design, processing, materials, manufacture, testing, performance, reliability, thermal management, and environmental considerations. For the specialist, who must build upon these foundations, each chapter includes a judicious selection of recommended further readings. For the autodidact, the scholar, or the flagellant, there are even homework problems to test your knowledge. Four chapters, covering optoelectronics, MEMS, RF packaging, and wafer-level packaging, lead the venturesome to the borders of today's knowledge, where they might glimpse the promised land, or just gape at the dark forests of ignorance.

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